REMARKS

Applicant has thoroughly considered the Examiner's remarks in the January 24, 2005 Office action and has amended the application to more clearly set forth the invention. Claims 1 and 5-8 have been amended by this Amendment B. Reconsideration of the application as amended and in view of the following remarks is respectfully requested.

In addition to correcting typographical errors in the specification, this Amendment B amends the specification and drawings to address the Examiner's rejection regarding the functional recitation in the specification and claim 1. Applicant has added more technical descriptions/explanations especially related to the advantages of the present invention, the technical effects achieved, and the technical problems solved by the present invention, which are distinct from the prior art. The amendments clarify, or fill out, the subject matter of the present application as filed, including the subject matter as shown in and described in connection with FIGS. 6 and 6A. Inasmuch as the present application supports the amendments to the specification and drawings, they do not constitute new matter.

Claims 1-8 stand rejected under 35 U.S.C. § 103 as being unpatentable over Spitz et al., U.S. Patent No. 6,060,776 in view of Spitz et al., U.S. Patent No. 6,667,545.

Amended claim 1 recites a solder platform 17 that has an anchor mechanism 11, which is equipped with an acclivitous shoulder 12 and a kink 13. According to the claim, the mechanism 11 can absorb the stress generated by epoxy package 8 and

provide a longer path for moisture to reach the die 16. As such, the invention prevents moisture from reaching the die 16 directly even if moisture enters the gap existing between the shoulder 12 and the passivative film 10.

Applicant submits the kink 13 is a unique technical feature of the subject invention and is not taught or suggested by any prior art, and the effects achieved by the kink 13 of the subject invention cannot be found in the cited references. More specifically, the prior art devices involve the problem of damaging the die 16 due to plastic deformation 22 generated by stress (referring to Figs. 7 and 7A and corresponding contents in the specification). However, the present invention can avoid the problem of damaging the die 16 and totally absorb stress by the unique design of the kink 13, the solder platform 17, and the base 18 (referring to Figs. 8 and 8A and corresponding contents in the specification). On the other hand, the present invention can create complete seal interface 23 and 24 in order to avoid any unwanted gap generated and improve the ability of the die 16 against the moisture entered and extend the lifetime of the die 16 (referring to Figs. 9 and 10 and corresponding contents in the specification). For these reasons, applicant submits claim 1, and claims 2-8 depending therefrom, are allowable over the cited art.

In view of the foregoing, applicant respectfully submit that claims 1-8 are in condition for allowance and respectfully request favorable reconsideration of this application as amended. The fact that applicant may not have specifically traversed any particular assertion by the Office should not be construed as indicating applicant's agreement therewith.

The Commissioner is hereby authorized to charge any deficiency or overpayment of any required fee during the entire pendency of this application to Deposit Account No. 19-1345.

Respectfully submitted,

Robert M. Bain, Reg. No. 36,736
SENNIGER POWERS
One Metropolitan Square, 16th Floor
St. Louis, Missouri 63102
(314) 231-5400

WEL/RMB/cjl

Amendments to the Drawings:

The attached sheets of drawings includes changes to FIGS. 6, 6A, 7, 7A, 8, 8A, 9, and 10. These sheets replace the original sheet including FIGS. 6 and 6A and add sheets including FIGS. 7, 7A, 8, 8A, 9, and 10. In particular, FIGS. 6 and 6A have been amended by adding the reference numeral 11, which indicates the anchor mechanism.

Attachment: Replacement Sheets